



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS7030-2EPA		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005350050						
<b>Package</b>		PG-TSDSO-14-22		<b>Weight*</b>		64.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.139	1.75	1.75	17519	17519
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		580	
	non noble metal	iron	7439-89-6	0.754	1.16		11602	
	non noble metal	copper	7440-50-8	30.617	47.11	48.34	471089	483416
wire	non noble metal	copper	7440-50-8	0.489	0.75	0.75	7530	7530
encapsulation	organic material	carbon black	1333-86-4	0.087	0.13		1343	
	plastics	epoxy resin	-	3.404	5.24		52376	
	inorganic material	silicondioxide	60676-86-0	25.603	39.39	44.76	393936	447655
leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25259	25259
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12556	12556
glue	plastics	epoxy resin	-	0.069	0.11		1061	
	noble metal	silver	7440-22-4	0.325	0.50	0.61	5004	6065
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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